

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT4041861

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KANDASAMY SHANMUGAM	08/18/2016
ARAVIND GANESAN	08/18/2016
HIMAMSHU GOPALAKRISHNA KHASNIS	08/18/2016
RECEIVING PARTY DATA	
Name:	SIGNALCHIP INNOVATIONS PRIVATE LIMITED
Street Address:	4C-116, 4TH CROSS,
Internal Address:	OMBR LAYOUT, BANASWADI,
City:	BANGALORE
State/Country:	INDIA
Postal Code:	560043
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15258994
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	THE LAW OFFICE OF AUSTIN BONDERER, PC
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NAME OF SUBMITTER:	D. AUSTIN BONDERER
SIGNATURE:	/D. Austin Bonderer/
DATE SIGNED:	09/07/2016
Total Attachments: 3	
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PATENT APPLICATION ASSIGNMENT AGREEMENT

THIS AGREEMENT is made this 18th day of August, 2016, by and between 1. Kandasamy Shanmugam with address at 4C-116, 4th Cross, OMR Layout, Banaswadi, Bangalore - 560043, 2. Aravind Ganesan with address at 101 Block 1, Harsha Meadows, Suddagunte Palya, C. V. Raman Nagar, Bangalore - 560093, Karnataka, India, and 3. Himamshu Gopalakrishna Khasnis with address at 110, 1st Cross, Ramakrishna Gardens, New BEL Road, RMV 2nd Stage, Bangalore - 560054, Karnataka, India, collectively (hereinafter "ASSIGNORS") and Signalchip Innovations Private Limited ("Assignee") whose address is 4C-116, 4th Cross, OMR Layout, Banaswadi, Bangalore - 560043, Karnataka, India and collectively the "Parties".

WHEREAS, Assignors have invented "METHOD AND SYSTEM OF RELAYING IN CELLULAR SYSTEMS" (the "Invention"), disclosed in an application for United States Letters Patent (the "Patent Application") identified below.

WHEREAS, Assignee wishes to acquire all right, title and interest in the Patent Application, and Assignors wishes to sell its interest in the Patent Application to Assignee.

NOW THEREFORE, in consideration of the mutual promises, covenants, warranties, and other good and valuable consideration set forth herein, the Parties agree as follows:

1. Patent Application.

The Patent Application can be identified by:

Application Number: To be filed

Date of filing: To be filed

Name(s) of inventor: Mr. Kandasamy Shanmugam, Mr. Aravind Ganesan, Mr. Himamshu Gopalakrishna Khasnis

Name of invention: METHOD AND SYSTEM OF RELAYING IN CELLULAR SYSTEMS

2. Assignment. Assignors hereby assign to Assignee, its successors, representatives and assigns, all right, title and interest in the Patent Application and in all divisions, renewals and continuations thereof, and in all letters patent granted thereon, including all reexaminations, extensions and reissues thereof. Assignors hereby request the Commissioner of Patents of the United States to issue all Letters Patent granted pursuant to the Patent Application to Assignee, its successors, representatives and assigns.

3. **Payment.** In consideration of the assignment of the Patent Application pursuant to this Agreement, and of the promises and covenants contained herein, Assignee shall pay to Assignors a fee in the amount of INR 5, payable in cash, and for other good and valuable consideration, the receipt of both which is hereby acknowledged.
4. **Assignor's Representations and Warranties.** Assignors hereby represent and warrant that they have the legal right and authority to execute this Agreement, and to validly assign the entire interest in the Patent Application to Assignee. Assignors further represent and warrant that they have not executed any other agreement that would conflict with the terms of this Agreement, nor shall they execute any such agreement in the future.
5. **Further Actions.** Assignors hereby agree to execute any further agreements and to take any further actions necessary to aid Assignee in perfecting its interest in the Patent Application, and in any letters patent granted thereon, and in enforcing any and all protections or privileges deriving from the Patent Application or from said letters patent.
6. **Governing Law.** This Agreement shall be construed in accordance with, and governed in all respects by, the laws of the State of Karnataka, India without regard to conflicts of law principles.
7. **Counterparts.** This Agreement may be executed in several counterparts, each of which shall constitute an original and all of which, when taken together, shall constitute one agreement.
8. **Severability.** If any part or parts of this Agreement shall be held unenforceable for any reason, the remainder of this Agreement shall continue in full force and effect. If any provision of this Agreement is deemed invalid or unenforceable by any court of competent jurisdiction, and if limiting such provision would make the provision valid, then such provision shall be deemed to be construed as so limited.
9. **Notice.** Any notice required or otherwise given pursuant to this Agreement shall be in writing and mailed certified return receipt requested, postage prepaid, or delivered by overnight delivery service, addressed as follows:

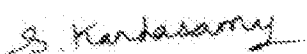
If to Assignors, at addresses given at Para 1 of this agreement.

If to Assignee: Signalchip Innovations Private Limited
4C-116, 4th Cross, OMBR Layout, Banaswadi, Bangalore - 560042, Karnataka, India.
10. **Headings.** The headings for section herein are for convenience only and shall not affect the meaning of the provisions of this Agreement.

11. Entire Agreement. This Agreement constitutes the entire agreement between Assignors and Assignee, and supersedes any prior understanding or representation of any kind preceding the date of this Agreement. There are no other promises, conditions, understandings or other agreements, whether oral or written, relating to the subject matter of this Agreement.
IN WITNESS WHEREOF, the parties have caused this Agreement to be executed the day and year first above written.

ASSIGNORS

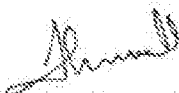
ASSIGNEE


Signalchip Innovations Private Limited

Kandasamy Shammugam



Aravind Ganesan



Himanshu Gopalakrishna Khasnis